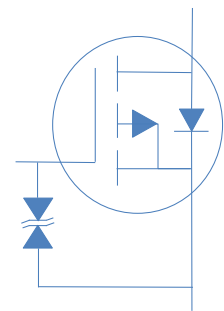
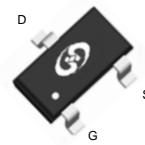


20V P-Ch Power MOSFET

V_{DS}		-20	V
$R_{DS(on),typ}$	$V_{GS}=4.5V$	37	m
$R_{DS(on),typ}$	$V_{GS}=2.5V$	55	m
$R_{DS(on),typ}$	$V_{GS}=1.8V$	65	m
I_D (Silicon Limited)		-4	A



Part Number	Package	Marking
HTJ440P02E	SOT-23	2E

Absolute Maximum Ratings at T_J 0 0 0

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	T_A	-4	A
		T_A	-3.5	
Drain to Source Voltage	V_{DS}	-	-20	V
Gate to Source Voltage	V_{GS}	-	± 8	V
Pulsed Drain Current	I_{DM}	-	-16	A
Power Dissipation	P_D	T_A	1.25	
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	R_{JA}	100	
Thermal Resistance Junction-Lead	R_{JL}	55	

Electrical Characteristics at T_j 0 0 0
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250 A	-20	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =-250 A	-0.3	-0.65	-1.0	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} =0V, V _{DS} =-16V, T _j	-	-	-1	A
		V _{GS} =0V, V _{DS} =-16V, T _j	-	-	-10	
Gate to Source Leakage Current	I _{GSS}	V _{GS} =±8V, V _{DS} =0V	-	-	±10	A
Drain to Source on Resistance	R _{DS(on)}	V _{GS} =-4.5V, I _D =-4A	-	37	44	m
		V _{GS} =-2.5V, I _D =-3A	-	55	70	
		V _{GS} =-1.8V, I _D =-1A	-	65	90	
Transconductance	g	V _{DS} =-5V, I _D =-4A	-	14	-	S

Dynamic Characteristics

Input Capacitance	C _{iss}		-	1059	-	pF
Output Capacitance	C _{oss}	V _{GS} =0V, V _{DS} 0	-	132	-	
	C _{rss}		-	127	-	
Total Gate Charge	Q _g		-	12.9	-	nC
Gate to Source Charge	Q _{gs}	V _{DD} =-10V, I _D =-4A, V _{GS} =-4.5V	-	1.8	-	
Gate to Drain (Miller) Charge	Q _{gd}		-	3.2	-	
Turn on Delay Time	t _{d(on)}		-	15	-	ns
Rise time	t _r	V _{DD} =-10V, I _D =-1A, V _{GS} =-4.5V,	-	30	-	
	t	R _G =6 Ω	-	35	-	
Fall Time	t		-	35	-	

Reverse Diode Characteristics

Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _F =-3A	-		-1.2	V
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Fig 1. Typical Output Characteristics

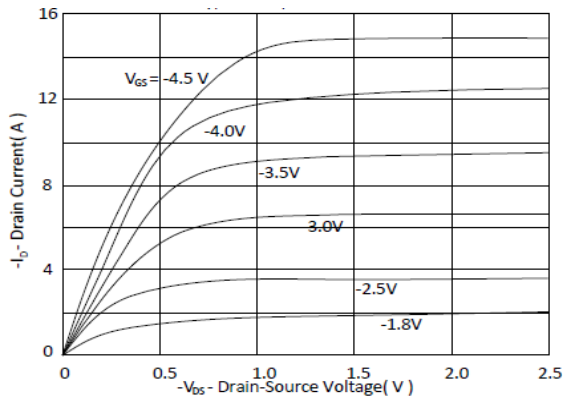


Figure 2. On-Resistance vs. Gate-Source Voltage

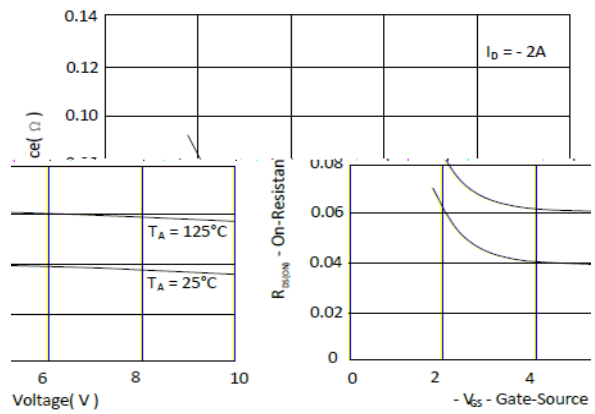


Figure 3. Gate Threshold Voltage v.s. Junction Temperature

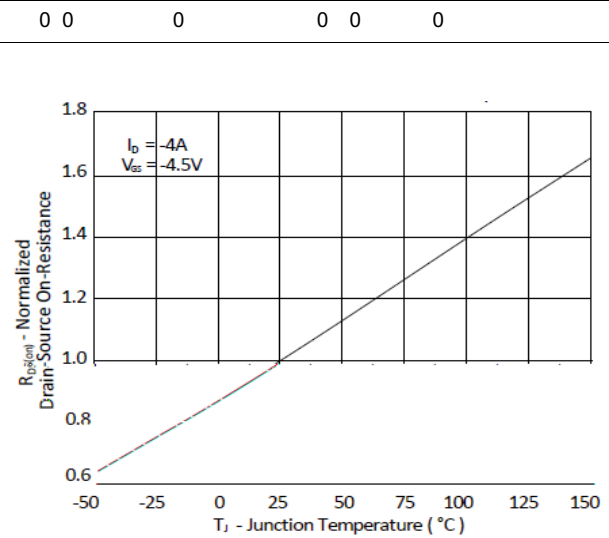
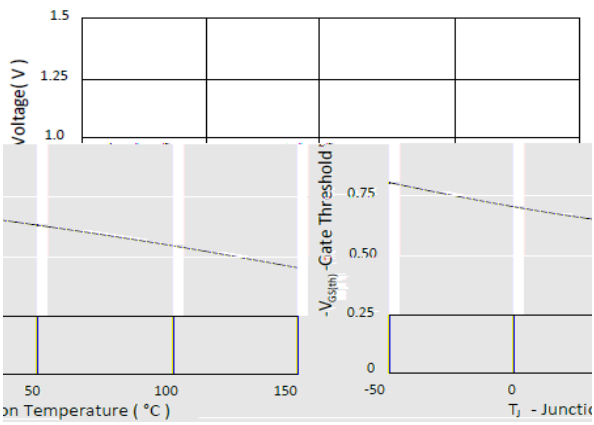


Figure 5. Typical Source-Drain Diode Forward Voltage

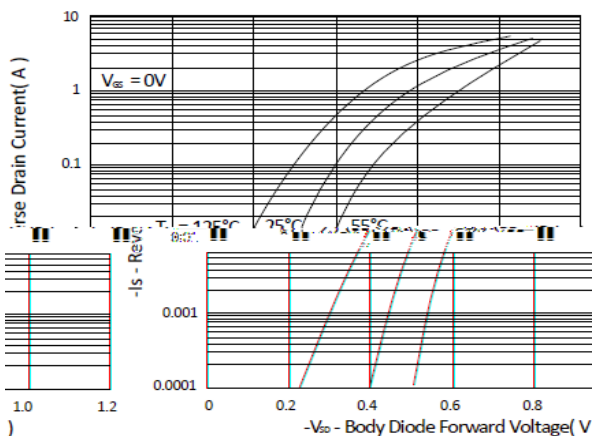
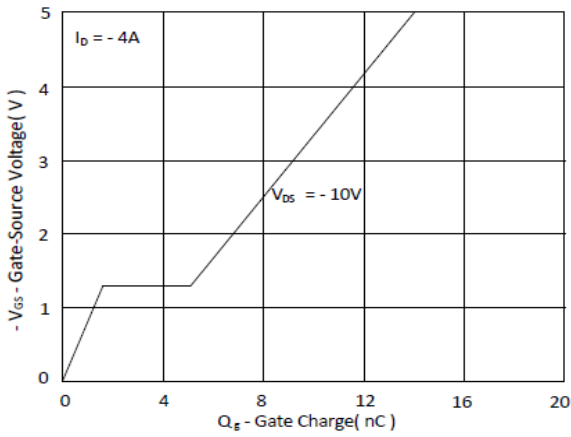


Figure 6. Typical Gate-Charge vs. Gate-to-Source Voltage



0 0 0 0 0

Figure 7. Typical Capacitance vs. Drain-to-Source Voltage

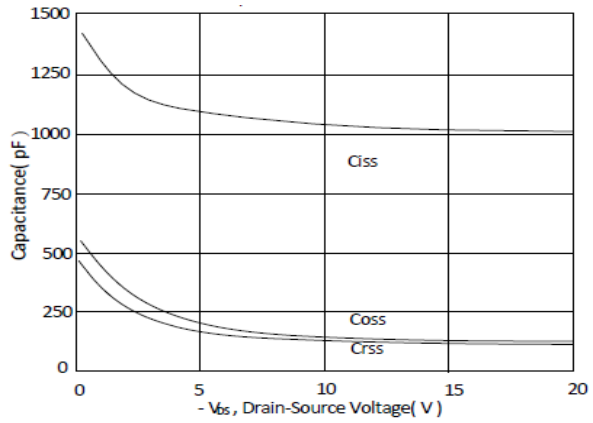
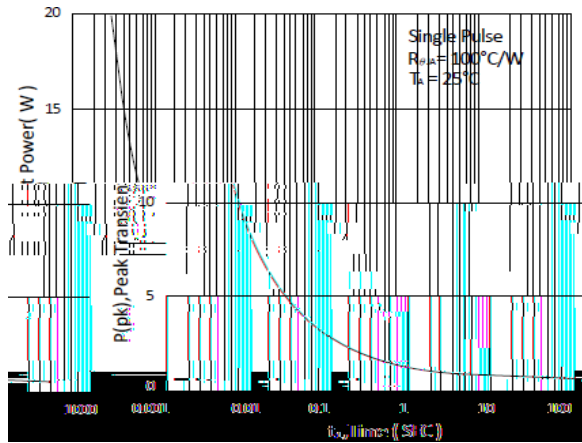
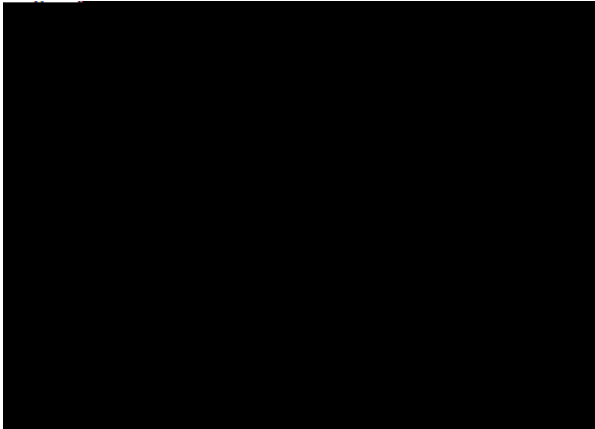
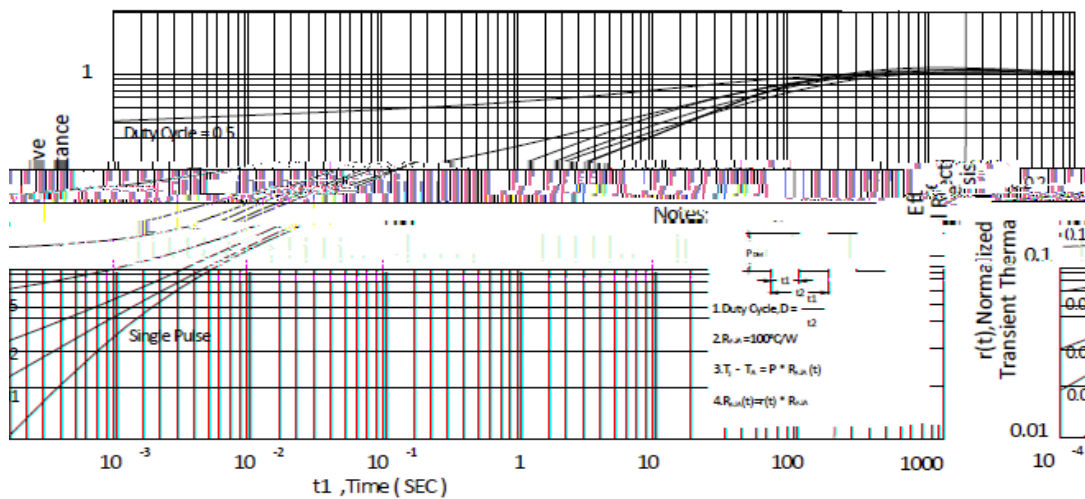


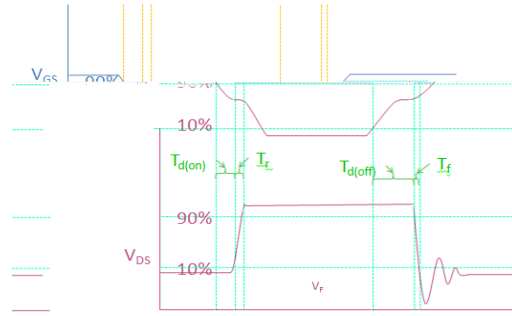
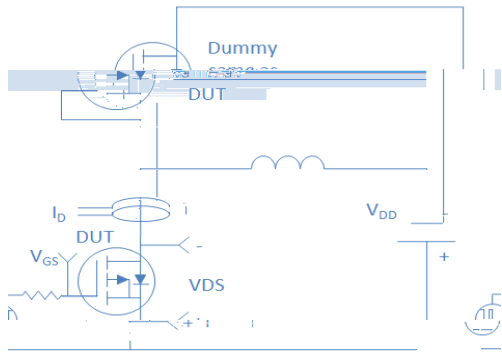
Figure 9. Single Pulse Maximum Power Dissipation



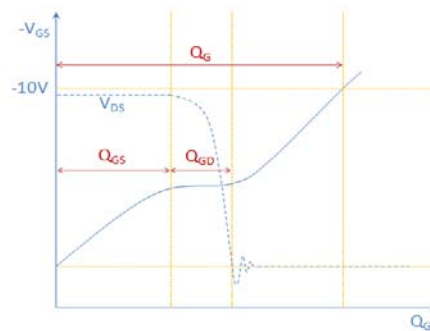
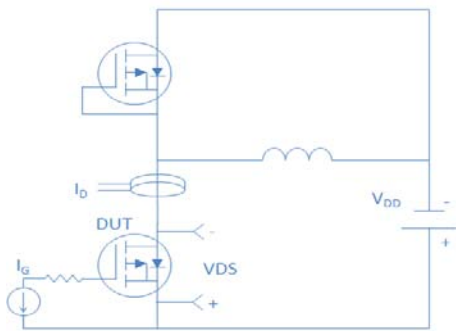
0 0 0 0 0 0 0 0



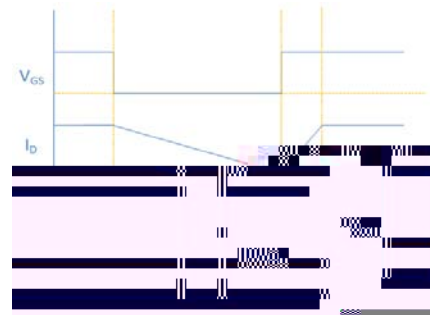
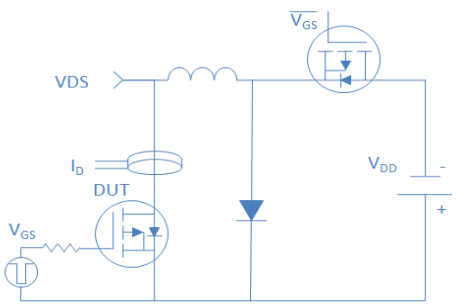
Inductive switching Test



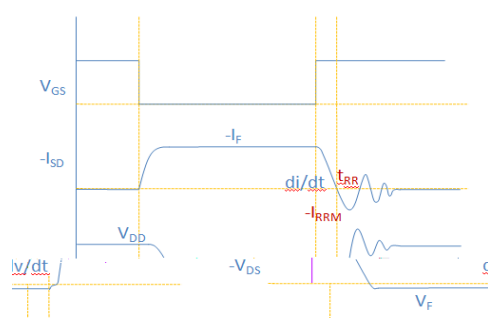
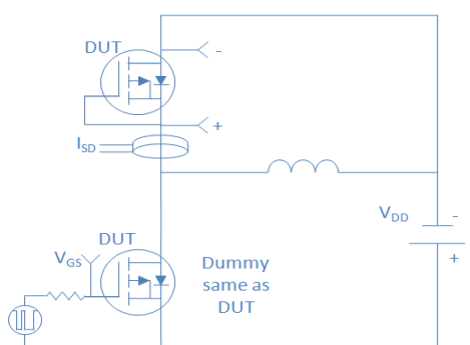
Gate Charge Test



Uclamped Inductive Switching (UIS) Test



Diode Recovery Test



Packa Outl

Ver 1.